

## **WCR380N65T/WCR380N65TF/ WCR380N65TH 650V N-Channel Super Junction MOSFET**

### **Description**

The WCR380N65T series is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance. This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. This device is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

### **Features**

- 700V@ $T_J=150^{\circ}\text{C}$
- Typ. $R_{DS(on)}=0.33\Omega$
- Low gate charge(typ.  $Q_g= 32\text{nC}$ )
- 100% avalanche tested
- 100%  $R_g$  tested

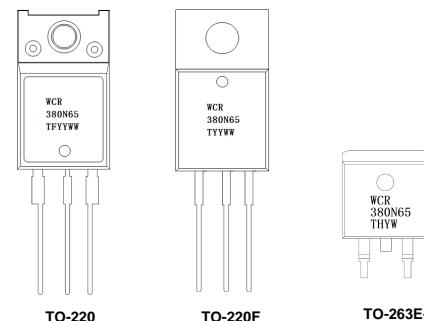
### **Order Information**

Device	Package	Marking	Units/Tube	Units/Real
WCR380N65T-3/T	TO-220	WCR380N65TYYWW	50	
WCR380N65TF-3/T	TO-220F	WCR380N65TFYYWW	50	
WCR380N65TH-3/TR	TO-263E-2	WCR380N65THYW		800

Note 1: WCR380N65T=Device code ; YY=Year ;WW=Week (A~z);

Note 2: WCR380N65TF=Device code ; YY=Year ;WW=Week (A~z);

Note 3: WCR380N65TH=Device code ; Y=Year ;W=Week (A~z);



TO-220      TO-220F      TO-263E-2

### **Absolution Maximum Ratings $T_A=25^{\circ}\text{C}$ unless otherwise noted**

Parameter	Symbol	WCR380N65T WCR380N65TH	WCR380N65TF	Unit
Drain-Source Voltage	$V_{DS}$	650		V
Gate-Source Voltage	$V_{GS}$	$\pm 30$		
Continuous Drain Current <sup>A</sup>	$I_D$	10.6		A
		6.7		
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	30		A
Single Pulsed Avalanche Energy <sup>C</sup>	$E_{AS}$	215		mJ
Avalanche Current <sup>B</sup>	$I_{AR}$	2.7		A
Repetitive Avalanche Energy <sup>B</sup>	$E_{AR}$	0.30		mJ
Power Dissipation	$P_D$	83	31.2	W
		0.66	0.25	
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55~150		°C
Lead Temperature	$T_L$	260		°C
<b>Thermal Resistance Ratings</b>				
Maximum Junction-to-Ambient	$R_{\theta JA}$	60	80	°C/W
Maximum Junction-to-Case	$R_{\theta JC}$	1.5	4	

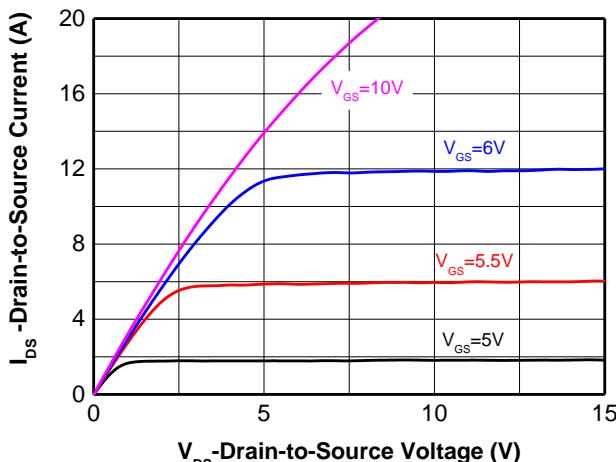
**Electronics Characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_{\text{D}} = 250\mu\text{A}, T_J = 25^\circ\text{C}$	650			V
		$V_{\text{GS}} = 0 \text{ V}, I_{\text{D}} = 250\mu\text{A}, T_J = 150^\circ\text{C}$		700		V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$			1	$\mu\text{A}$
Gate-to-source Leakage Current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 30 \text{ V}$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{GS}} = V_{\text{DS}}, I_{\text{D}} = 250\mu\text{A}$	2.5		4.5	V
Drain-to-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 5\text{A}$ (NOTE D)		0.33	0.38	$\Omega$
Forward Transconductance	$G_{\text{fs}}$	$V_{\text{DS}} = 40\text{V}, I_{\text{D}} = 5\text{A}$			20	s
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0 \text{ V}, f = 1.0 \text{ MHz}, V_{\text{DS}} = 400 \text{ V}$		1140		pF
Output Capacitance	$C_{\text{oss}}$			30		
Reverse Transfer Capacitance	$C_{\text{rss}}$			4		
Total Gate Charge	$Q_{\text{G}(\text{TOT})}$	$V_{\text{GS}} = 10 \text{ V}, V_{\text{DS}} = 480 \text{ V}, I_{\text{D}} = 10\text{A}$		32		nC
Gate-to-Source Charge	$Q_{\text{GS}}$			7.3		
Gate-to-Drain Charge	$Q_{\text{GD}}$			14.7		
Gate resistance	$R_g$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$		7.4		$\Omega$
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 400 \text{ V}, I_{\text{D}} = 11\text{A}, R_{\text{G}}=20 \Omega$		21		ns
Rise Time	$t_r$			38		
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			84		
Fall Time	$t_f$			27		
<b>Drain to Source Diode Characteristics and Maximum Ratings</b>						
Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}} = 0 \text{ V}, I_{\text{S}} = 9.5\text{A}$			1.5	V
Body-Diode Continuous Current	$I_{\text{S}}$				10	A
Body-Diode Pulsed Current	$I_{\text{SM}}$				30	A
Body Diode Reverse Recovery Time	$T_{\text{rr}}$	$I_F=9.5\text{A}, dI/dt=100\text{A/us}, V_{\text{DS}}=100\text{V}$		347		nS
Body Diode Reverse Recovery Charge	$Q_{\text{rr}}$			4		uC
Peak reverse recovery Current	$I_{\text{rrm}}$			23		A

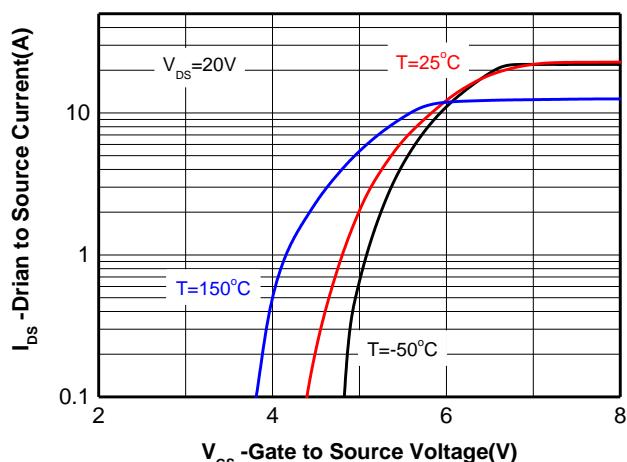
**NOTES:**

- A. Drain current limited by maximum junction temperature. Maximum duty cycle  $D=0.75$
- B. Pulse width limited by maximum junction temperature
- C.  $L=60\text{mH}, I_{\text{AS}}=2.7\text{A}, V_{\text{DD}}=50\text{V}$ , Starting  $T_J=25^\circ\text{C}$
- D. Pulse Test: Pulse width  $\leq 300\text{us}$ , Duty Cycle  $\leq 2\%$
- E. Essentially Independent of Operating Temperature Typical Characteristics
- F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heat sink, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=150^\circ\text{C}$ . The SOA curve provides a single pulse rating.
- G. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ .

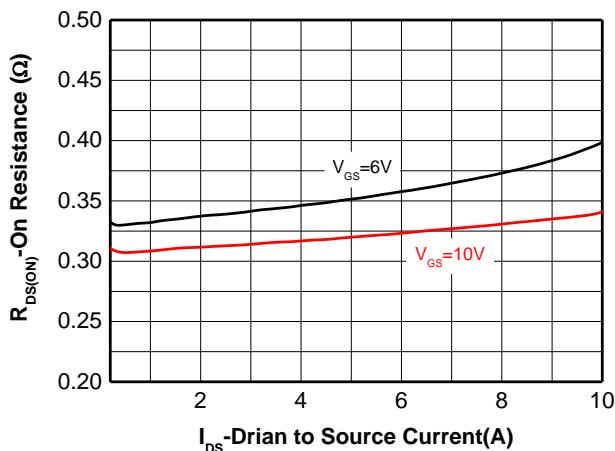
Typical Characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise noted)



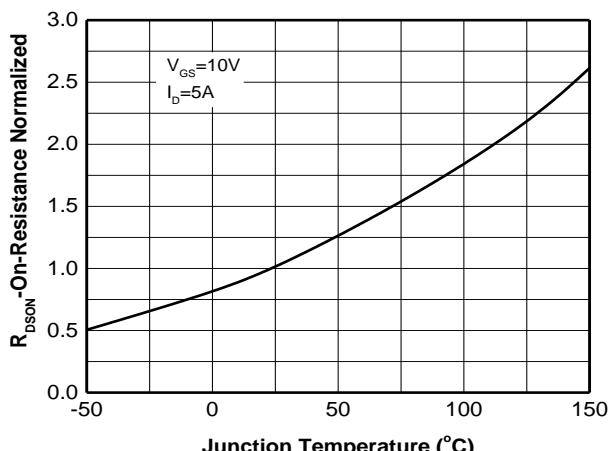
Output characteristics



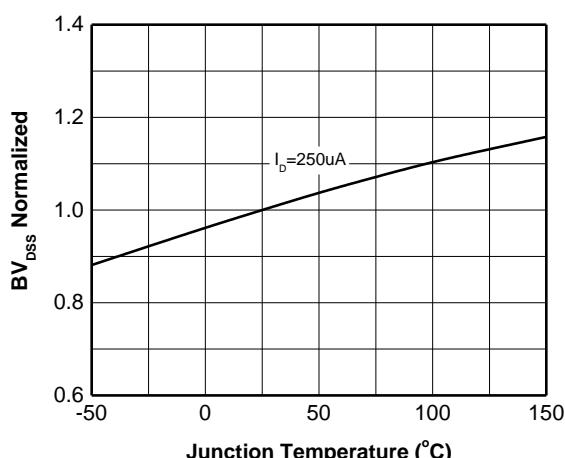
Transfer characteristics



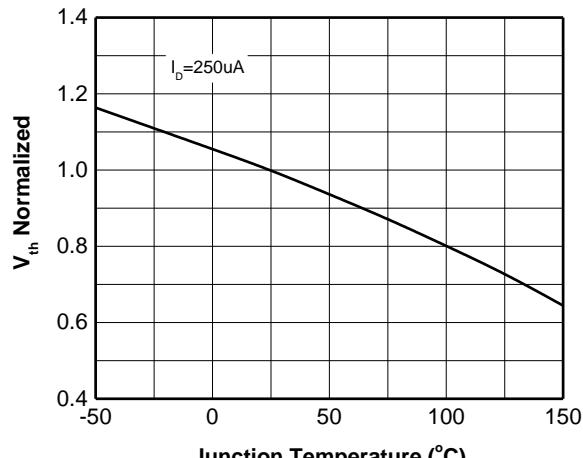
On-Resistance vs. Drain current



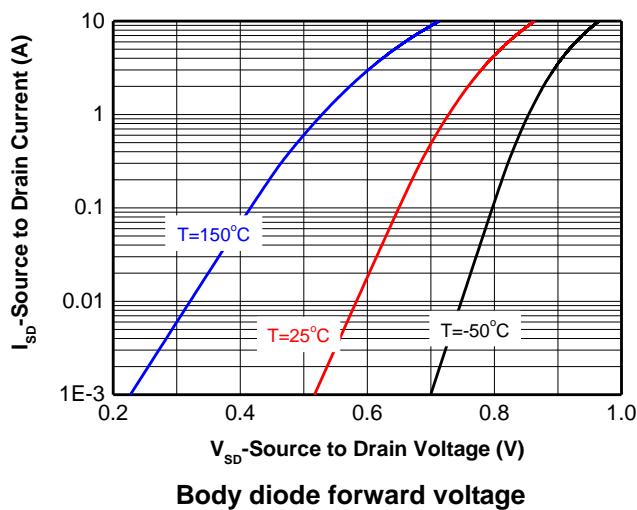
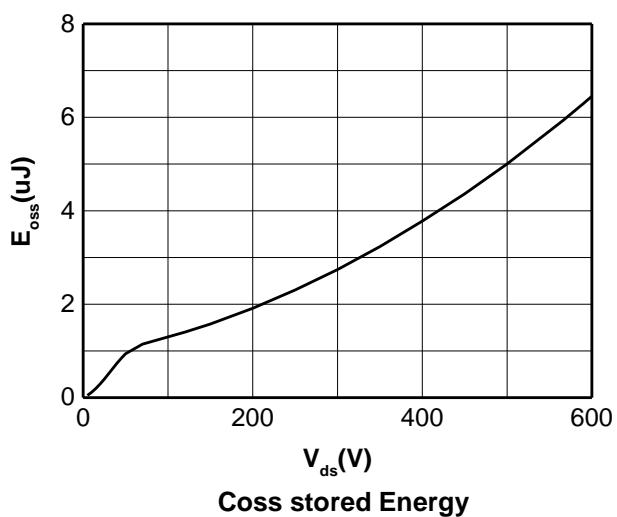
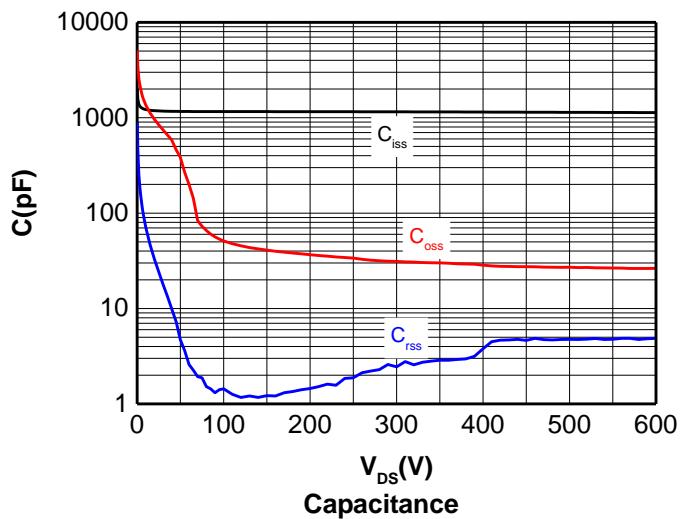
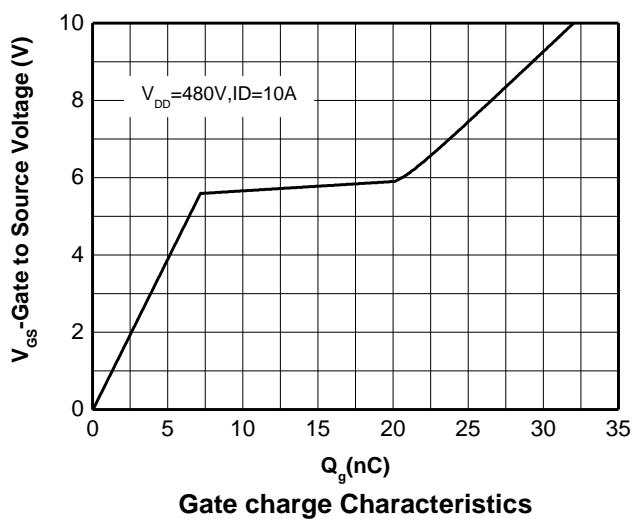
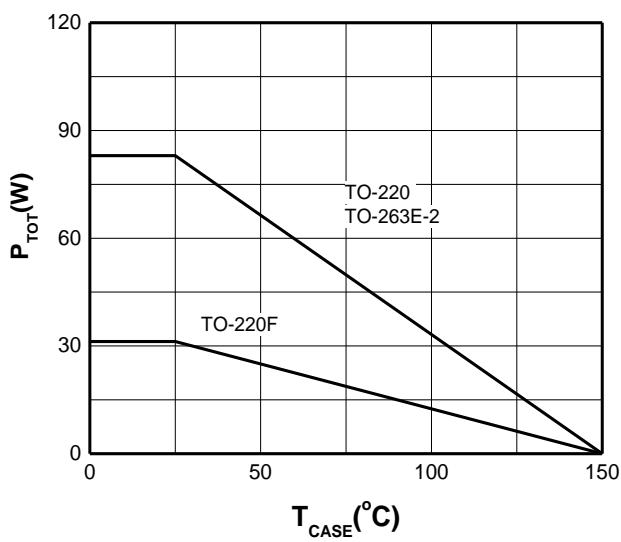
On-Resistance vs. Junction temperature

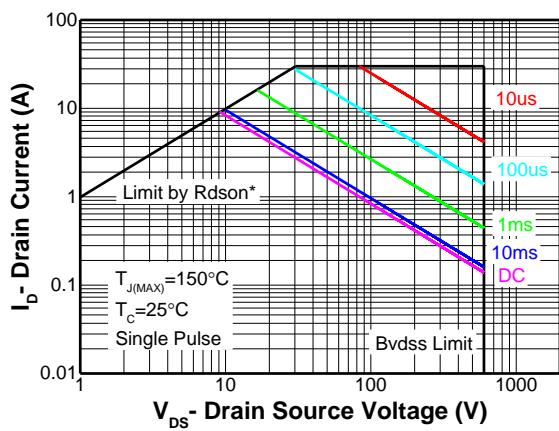


Breakdown Voltage vs. Junction temperature

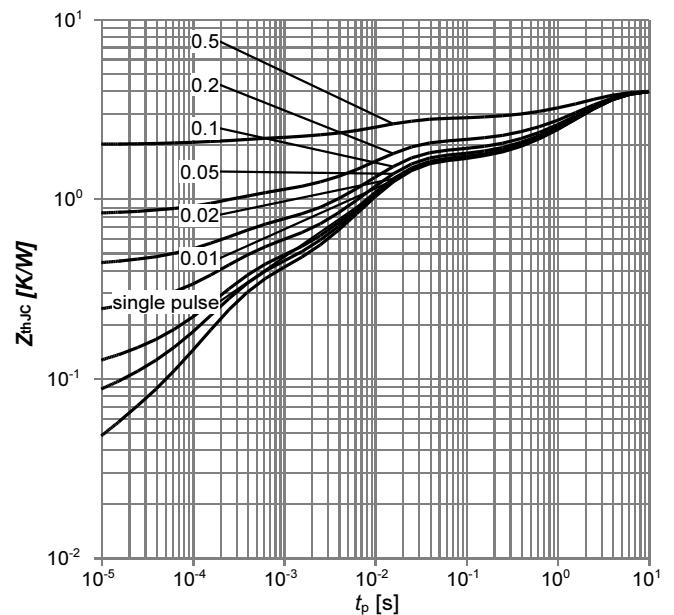
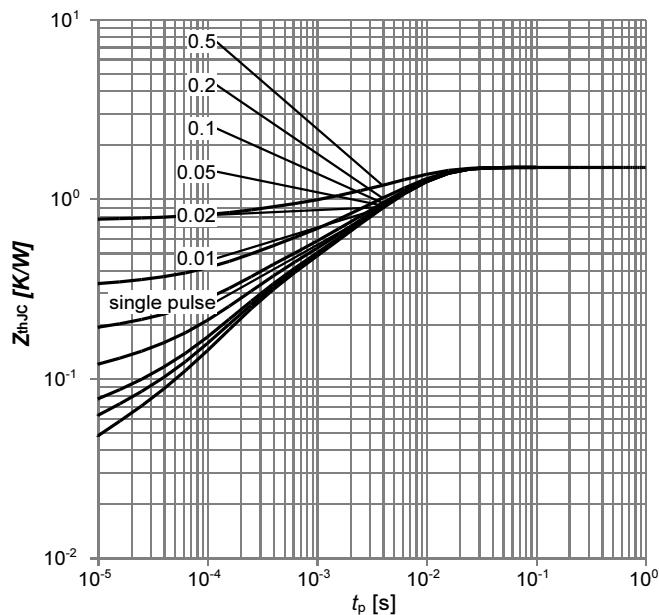
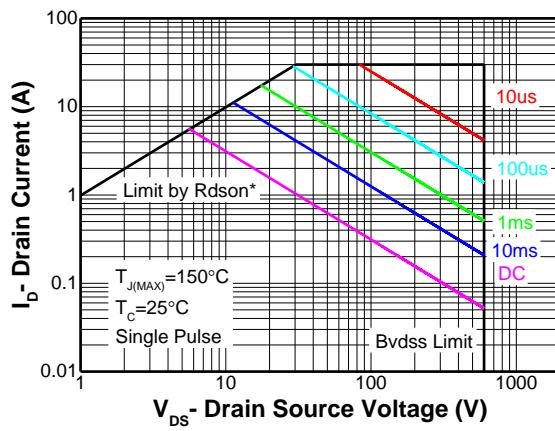


Threshold voltage vs. Junction temperature

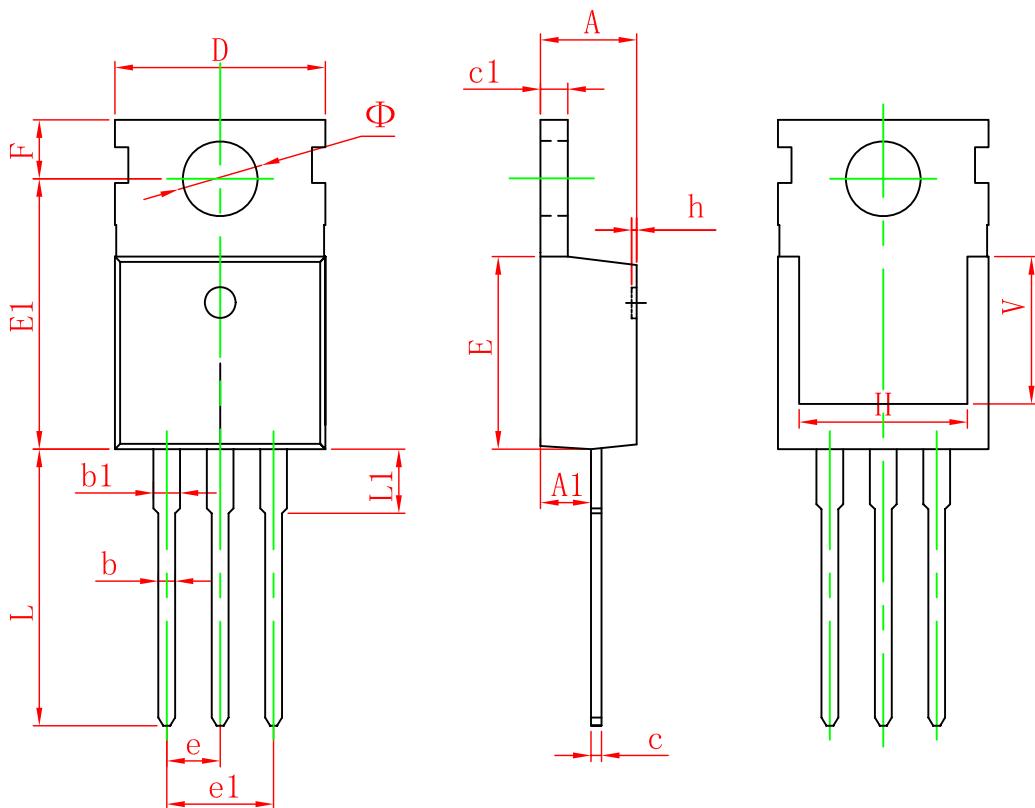

**Body diode forward voltage**

**Coss stored Energy**

**Capacitance**

**Gate charge Characteristics**

**Power dissipation**



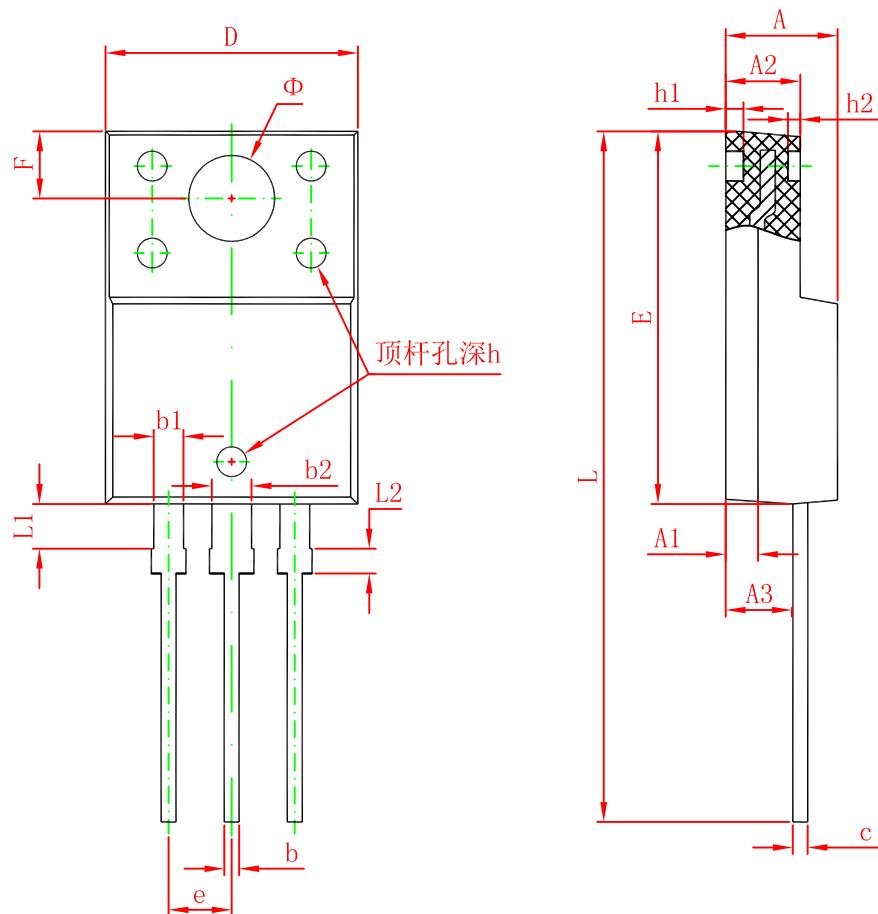
**TO-220 TO-263E-2**  
**Safe operating area(Note F)**



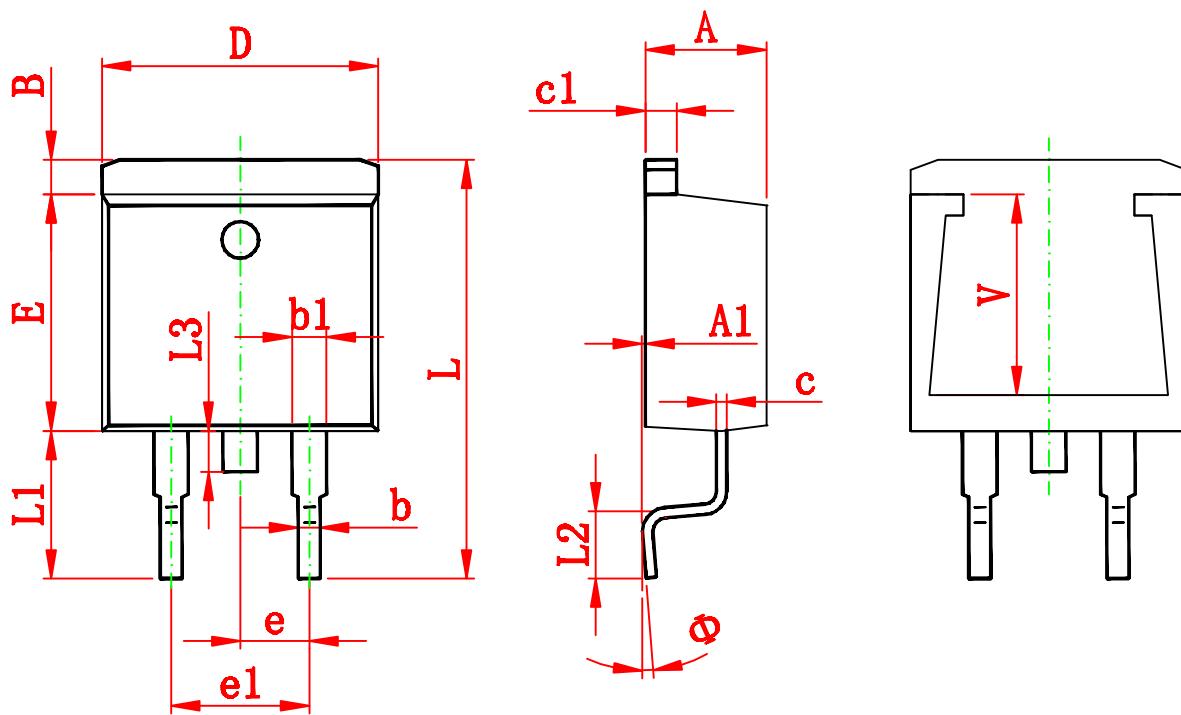
**Transient thermal response (Junction-to-Case)(Note F)**

**Package outline dimensions**
**TO-220-3L**


Symbol	Dimensions in Millimeters	
	Min.	Max.
A	4.40	4.60
A1	2.25	2.55
b	0.71	0.91
b1	1.17	1.37
c	0.33	0.65
c1	1.20	1.40
D	9.91	10.25
E	8.95	9.75
E1	12.65	12.95
e	2.54 Typ.	
e1	4.98	5.18
F	2.65	2.95
H	7.90	8.10
h	0.00	0.30
L	12.90	13.40
L1	2.85	3.25
V	6.90 Ref.	
Φ	3.40	3.80

**Package outline dimensions**
**TO-220F-3L**


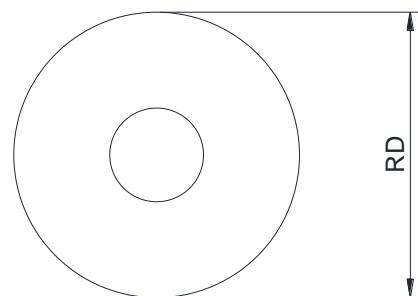
Symbol	Dimensions in Millimeters	
	Min.	Max.
A	4.30	4.70
A1	1.30 Ref.	
A2	2.80	3.20
A3	2.50	2.90
b	0.50	0.75
b1	1.10	1.35
b2	1.50	1.75
c	0.50	0.75
D	9.96	10.36
E	14.80	15.20
e	2.54 Typ.	
F	2.70 Ref.	
Φ	3.50 Ref.	
h	0.00	0.30
h1	0.80 Ref.	
h2	0.50 Ref.	
L	28.00	28.40
L1	1.70	1.90
L2	0.90	1.10

**Package outline dimensions**
**TO-263E-2L**


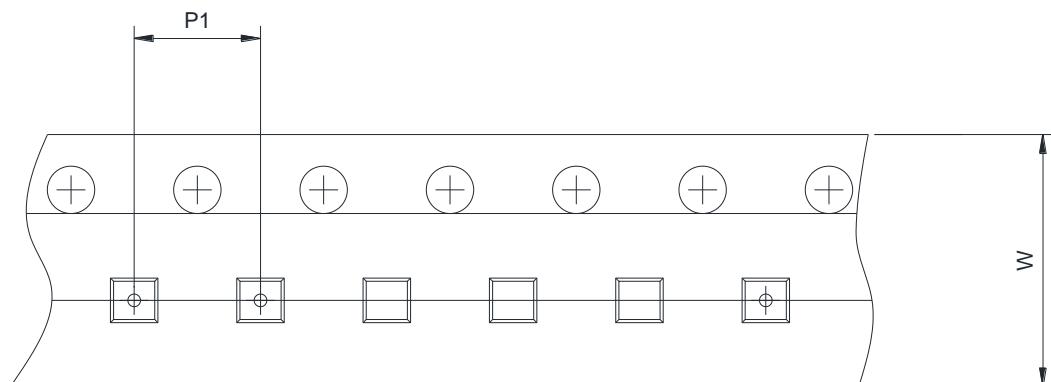
Symbol	Dimensions in Millimeters	
	Min.	Max.
A	4.47	4.67
A1	0.00	0.15
B	1.12	1.42
b	0.71	0.91
b1	1.17	1.37
c	0.31	0.53
c1	1.17	1.37
D	10.01	10.31
E	8.50	8.90
e	2.54 Typ.	
e1	4.98	5.18
L	14.94	15.50
L1	4.95	5.45
L2	2.34	2.74
L3	1.30	1.70
Φ	0 °	8 °
V	6.60 Ref.	

**TAPE AND REEL INFORMATION**
**TO-263E-2L**

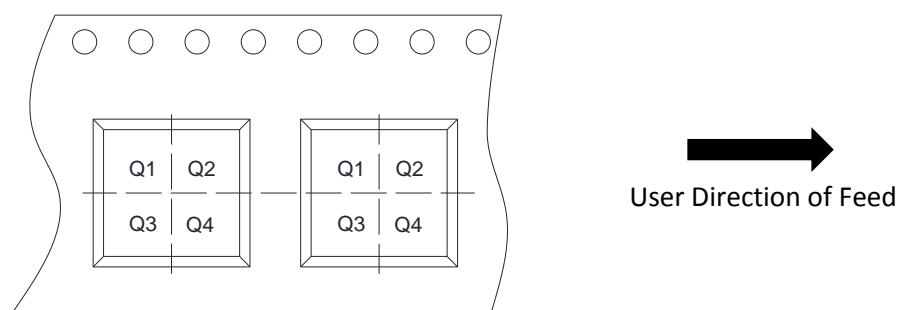
Reel Dimensions



Tape Dimensions



Quadrant Assignments For PIN1 Orientation In Tape



<b>RD</b>	Reel Dimension	<input type="checkbox"/> 7 inch <input checked="" type="checkbox"/> 13 inch
<b>P1</b>	Pitch between successive cavity centers	<input type="checkbox"/> 4 mm <input type="checkbox"/> 8 mm <input checked="" type="checkbox"/> 16 mm
<b>W</b>	Overall width of the carrier tape	<input type="checkbox"/> 8 mm <input type="checkbox"/> 12 mm <input checked="" type="checkbox"/> 24 mm
<b>Pin1</b>	Pin1 Quadrant	<input type="checkbox"/> Q1 <input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4